

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
(Docket No. 98010CONDIV)

Applicant(s): BRUSIC et al.

Serial No.: Not yet assigned

Filing Date: Filed Herewith

Title: CHEMICAL MECHANICAL POLISHING  
SLURRY USEFUL FOR COPPER  
SUBSTRATES

Certification under 37 CFR 1.10

I, Mariejose Monsalve, hereby certify that this correspondence, and any other documents and/or fees referred to as enclosed herein, are being deposited in an envelope with the U.S. Postal Service "Express Mail Post Office to Addressee" service on 09- JUL - 03 and addressed to the Mail Stop/Address indicated below.



(Signature of person mailing paper)

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INFORMATION DISCLOSURE STATEMENT

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA, 22313-1450

Pursuant to 37 C.F.R. §1.56, §1.97 and §1.98, Applicant(s) request(s) that references cited in the prior application, US Serial No. 10/145,357 filed on May 14, 2002, be made of record in the present divisional application. Enclosed, for the Examiner's convenience, are copies of lists of references considered and/or cited by the Examiner in the parent application's file. In accordance with the provisions of Rule 1.98(d), copies of these references are not enclosed, however, applicant can provide them upon request.

The right to later set forth how the claimed invention is distinguished over the disclosure of any document or other art, including the disclosures of the art and documents referenced herein, and those that may be cited by the Examiner in rejecting a claim in the instant patent application is reserved.

The referenced documents are cited to ensure that the Examiner has the benefit of all the information of which the Applicants are aware which may be helpful to the U.S. Patent and Trademark Office in its examination of this application. The Examiner is requested to review the documents and determine the extent of materiality of the disclosures with respect to the present invention.

Respectfully submitted,



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Atty. Docket No.

MMD98010CON

Serial No.

To Be Assigned

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT  
(Use several sheets if necessary)

Applicant:

Vlasta Brusic Kaufman et al.

Filing Date:

May 14, 2002



## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
TE		3,385,682	5/28/68	Lowen			
		4,086,176	4/25/78	Ericson et al.			
		4,671,851	6/9/87	Beyer et al.			
		4,789,648	12/6/88	Chow et al.			
		4,910,155	3/20/90	Cote et al.			
		4,944,836	7/31/90	Beyer et al.			
		4,956,313	9/11/90	Cote et al.			
		5,137,544	8/11/92	Medellin			
		5,157,876	10/27/92	Medellin			
		5,209,816	5/11/93	Yu et al.			
		5,244,523	9/14/93	Tollini			
		5,340,370	8/23/94	Cadien et al.			
		5,354,490	10/11/94	Yu et al.			
		5,391,258	2/21/95	Brancaleoni et al.			
		5,476,606	12/19/95	Brancaleoni et al.			
		5,527,423	6/18/96	Neville et al.			
		5,575,837	11/19/96	Kodama et al.			
		5,700,383	12/23/97	Fellner et al.			
		5,735,963	4/7/98	Obeng			
		5,800,577	9/1/98	Kido			
TE		5,783,489	7/21/98	Kaufman et al.			

EXAMINER

DATE CONSIDERED

*Timothy V. Eley**12/01/02*

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609;  
 Draw line through citation if not in conformance and not considered. Include copy of this form with  
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Applicant:

Vlasta Brusic Kaufman et al.

Filing Date:

May 14, 2002

Group:

3724

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
TR		5,770,095	6/23/98	Sasaki et al.			
/		5,922,091	7/13/99	Tsai et al.			
/		5,407,526	4/18/95	Danielson			
/		6,063,306	5/16/00	Kaufman			
/		5,478,435	12/26/95	Murphy et al.			
TR		5,858,813	1/12/99	Scherber			

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
TR		Hei 8[1996]-83780	3/15/95	Japan			X	
		GB 1,198,312	7/8/70	Great Britain				
		EP O 811 665	12/10/97	EPO				
		EP O 846 742	6/10/98	EPO				
		EP O 811 666	12/10/97	EPO				
		WO 97/47030	12/11/97	WO				
		WO 98/23408	6/5/98	WO				
		WO 98/26025	6/18/98	WO				
		WO 98/04646	2/5/98	WO				
TR		WO 97/43087	11/20/97	WO				

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Thomas V. Ely

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FORM PTO-1449  
(Rev. 2-32)

U.S. Department of Commerce  
Patent and Trademark Office

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7224

**U.S. PATENT DOCUMENTS**

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate

**FOREIGN PATENT DOCUMENTS**

		Document Number	Date	Country	Class	Subclass	Translation
							Yes
TR		DE 2847267	5/8/80	Germany	/	/	X
TR		JP 49109223 (Abstract)	10/17/74	Japan	/	/	

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc).**

TR		Carpio et al., <i>Journal: TSF (Thin Solid Films)</i> , Article: 6649, Initial Study on Copper CMP Slurry Chemistries (1995)
		Hirabayashi et al., February 22-23, 1996 CMP-MIC Conference - 96ISMIC - 100P, pp. 119-123, Chemical Mechanical Polishing of Copper Using a Slurry Composed of Glycine and Hydrogen Peroxide (1996)
		Luo et al., February 22-23, 1996 CMP-MIC Conference - 96ISMIC - 100P, pp. 145-151, Chemical-Mechanical Polishing of Copper In Acid Media (1996)
		Steigerwald et al. <i>J. Electrom. Soc.</i> , Vol. 142, No. 7, pp. 2379-2385, Electrochemical Potential Measurements During the Chemical-Mechanical Polishing of Copper Thin Films (1995)
		Steigerwald, et al., Materials Chemistry and Physics, pp. 217-228, Chemical Processes in the chemical mechanical polishing of copper (1995).
TR		Steigerwald, et al., Electrochemical Potential Measurements during the Chemical Mechanical Polishing of Copper Thin Films, Mat. Res. Soc. Symp. 337, 133 (1994).

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